

## Searching PAJ

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If you want to conduct a Number Search, please click on the button to the right.

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If you use the AND/OR operation, please leave a SPACE between keywords.

One letter word or Stopwords are not searchable.

wire bond

AND

AND

chip die stack

OR

AND

capillary tool bonder tip

OR

AND

**Date of publication of application** — e.g. 19980401 - 19980405

19900101

-

20010512

AND

**IPC** — e.g. D01B7/04 A01C11/02

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## Searching PAJ

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## WEST Search History

DATE: Thursday, June 19, 2003

**Set Name Query**

side by side

**Hit Count Set Name**

result set

*DB=USPT,PGPB,JPAB,EPAB,DWPI,TDBD; PLUR=YES; OP=ADJ*

L8	L7 and (bump or bumped)	19	L8
L7	L6 and ball near (bond or bonded or bonding)	39	L7
L6	L5 and integrated circuit	260	L6
L5	L4 and wire near (bond or bonder or bonded or bonding)	313	L5
L4	L3 and (angle or angled or incline or inclined or inclination or offset)	319	L4
L3	L2 and stack	761	L3
L2	L1 and (ball or bump)	3167	L2
L1	(wire or ball) near (bond or bonder or bonded or bonding) and (chip or die) near (multiple or plural or plurality or stack or stacked)	5140	L1

END OF SEARCH HISTORY

# WEST Search History

DATE: Thursday, June 19, 2003

**Set Name Query**  
side by side

**Hit Count Set Name**  
result set

*DB=USPT,PGPB,JPAB,EPAB,DWPI,TDBD; PLUR=YES; OP=ADJ*

L17	l16 and (program or programmed or programming or programmable)	24	L17
L16	L15 and l3	65	L16
L15	L14 and (control or controlled or controller or controlling or program)	1646	L15
L14	L13 and (chip or die or integrated circuit)	2823	L14
L13	(wire) near (bond or bonder or bonded or bonding) and capillary	4759	L13
L12	l11 not l10	26	L12
L11	l6 and capillary	40	L11
L10	l7 and capillary	14	L10
L9	l7 not l8	20	L9
L8	L7 and (bump or bumped)	19	L8
L7	L6 and ball near (bond or bonded or bonding)	39	L7
L6	L5 and integrated circuit	260	L6
L5	L4 and wire near (bond or bonder or bonded or bonding)	313	L5
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